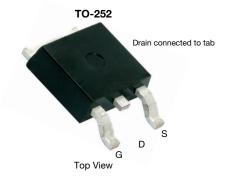


Vishay Siliconix

# Automotive N-Channel 60 V (D-S) 175 °C MOSFET

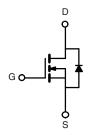
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}\left(\Omega\right)$ at $V_{GS}$ = 10 V	0.022			
$R_{DS(on)}\left(\Omega\right)$ at $V_{GS}$ = 4.5 V	0.033			
I <sub>D</sub> (A)	25			
Configuration	Single			
Package	TO-252			



#### FEATURES

- TrenchFET<sup>®</sup> power MOSFET
- Package with low thermal resistance
- 100 %  $R_{\rm q}$  and UIS tested
- AEC-Q101 qualified <sup>d</sup>
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (To	<sub>c</sub> = 25 °C, unles	s otherwise noted	)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	60	v
Gate-Source Voltage		V <sub>GS</sub>	± 20	v
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	1	25	
	T <sub>C</sub> = 125 °C	I <sub>D</sub>	20	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	25	A
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	100	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	24	
Single Pulse Avalanche Energy		E <sub>AS</sub>	28	mJ
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	Р	62	w
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	20	vv v
Operating Junction and Storage Temperature Ran	ge	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	50	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	2.4	0/₩

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					1		1
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μΑ	60	-	-	v
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$		1.5	2.0	2.5	v
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$0 \text{ V}, \text{V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1.0	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 125 °C	-	-	50	μA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	250	-
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	25	-	-	Α
		$V_{GS} = 10 V$	I <sub>D</sub> = 20 A	-	0.018	0.022	
Drain-Source On-State Resistance <sup>a</sup>	Б	$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	-	-	0.039	
Drain-Source On-State Resistance "	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	-	-	0.049	Ω
		$V_{GS} = 4.5 V$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 25 °C	-	0.027	0.033	
Forward Transconductance <sup>a</sup>	<b>g</b> fs	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 12 A	-	32	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	1580	1975	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 25 V$ , f = 1 MHz	-	305	382	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	130	163	
Total Gate Charge <sup>c</sup>	Qg			-	33	50	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{GS} = 10 V$	$V_{DS} = 30 \text{ V}, I_D = 25 \text{ A}$	-	5.3	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	6.8	-	
Gate Resistance	Rg		f = 1 MHz	0.5	1.3	3.3	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	8	12	
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> =	= 30 V, $R_{L}$ = 1.2 $\Omega$	-	10	15	1
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 25 \text{ A},$	$V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	24	36	ns
Fall Time <sup>c</sup>	t <sub>f</sub>	]		-	6	9	]
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	100	Α
Forward Voltage	V <sub>SD</sub>	I	25 A, V <sub>GS</sub> = 0 V	-	0.9	1.5	V

Notes

a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

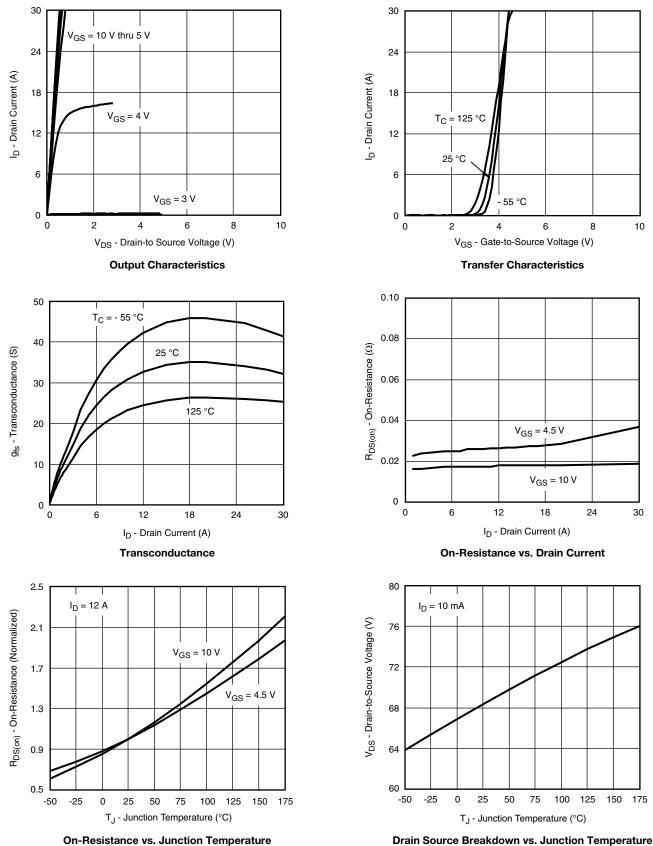
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SQD25N06-22L

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### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



S15-1873-Rev. D, 10-Aug-15

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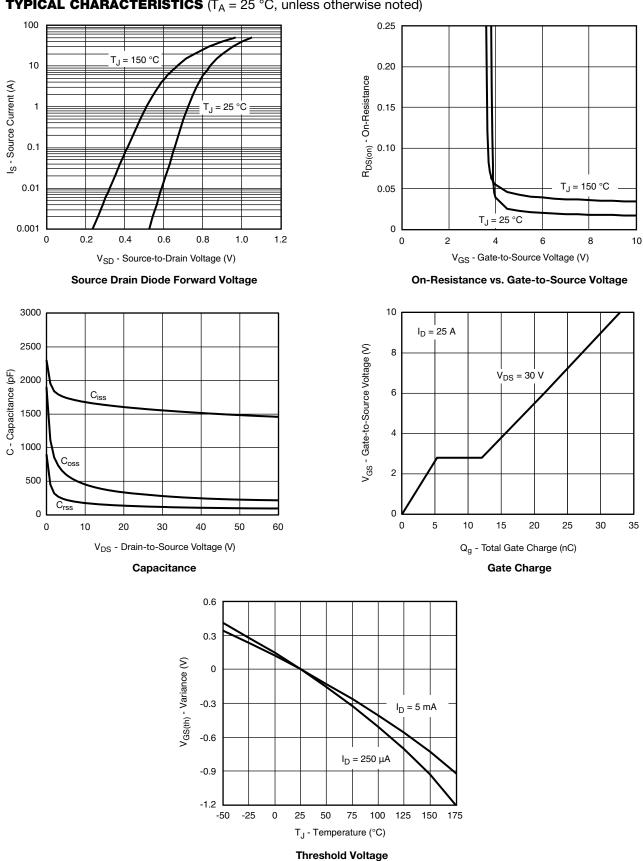
Document Number: 65360

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TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)

S15-1873-Rev. D, 10-Aug-15

4

Document Number: 65360

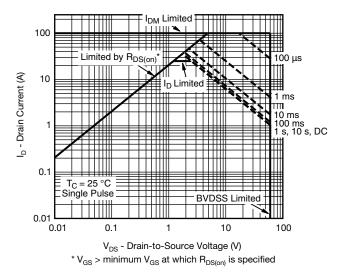
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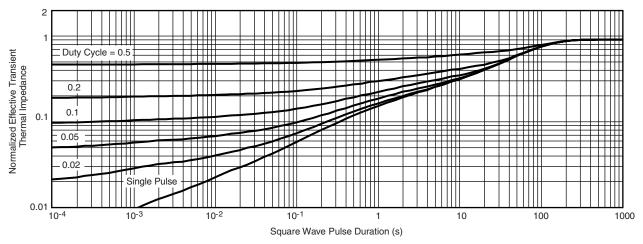
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### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Safe Operating Area

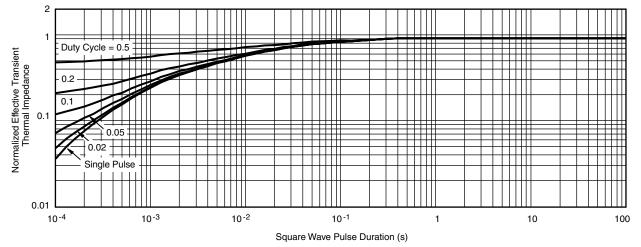


Normalized Thermal Transient Impedance, Junction-to-Ambient



## Vishay Siliconix

### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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# SQD25N06-22L

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REVISION	HISTORY <sup>a</sup>	
REVISION	DATE	DESCRIPTION OF CHANGE
D	04-Aug-15	Revised R <sub>g</sub> minimum limit

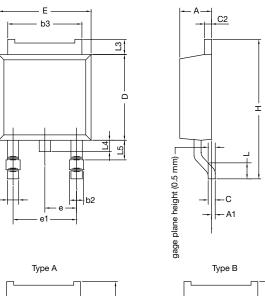
Note

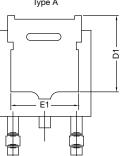
a. As of April 2014



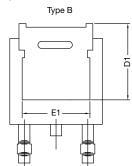


TO-252AA Case Outline





b



MIN.   2.18   -   0.64   0.76   4.95   0.46   0.46   5.97   4.10	MAX. 2.38 0.127 0.88 1.14 5.46 0.61 0.89 6.22	MIN. 0.086 - 0.025 0.030 0.195 0.018 0.018 0.235	MAX. 0.094 0.005 0.035 0.045 0.215 0.024 0.035 0.245
- 0.64 0.76 4.95 0.46 0.46 5.97 0.64 0.65 0.65 0.65 0.65 0.65 0.65 0.65 0.65	0.127 0.88 1.14 5.46 0.61 0.89 6.22	- 0.025 0.030 0.195 0.018 0.018	0.005 0.035 0.045 0.215 0.024 0.035
0.64     0.76       4.95     0.46       0.46     0.46       5.97     0.46	0.88 1.14 5.46 0.61 0.89 6.22	0.025 0.030 0.195 0.018 0.018	0.035 0.045 0.215 0.024 0.035
0.76 4.95 0.46 0.46 5.97	1.14 5.46 0.61 0.89 6.22	0.030 0.195 0.018 0.018	0.045 0.215 0.024 0.035
4.95 0.46 0.46 5.97	5.46 0.61 0.89 6.22	0.195 0.018 0.018	0.215 0.024 0.035
0.46 0.46 5.97	0.61 0.89 6.22	0.018 0.018	0.024 0.035
0.46 5.97	0.89 6.22	0.018	0.035
5.97	6.22		
		0.235	0.245
4.10			0.240
	-	0.161	-
6.35	6.73	0.250	0.265
4.32	-	0.170	-
9.40	10.41	0.370	0.410
2.28 BSC		0.090	BSC
4.56 BSC		0.180	BSC
1.40	1.78	0.055	0.070
0.89	1.27	0.035	0.050
-	1.02	-	0.040
1.01	1.52	0.040	0.060
	4.32 9.40 2.28 B 4.56 B 1.40 0.89 -	4.32     -       9.40     10.41       2.28 BSC     4.56 BSC       1.40     1.78       0.89     1.27       -     1.02	4.32     -     0.170       9.40     10.41     0.370       2.28 BSC     0.090       4.56 BSC     0.180       1.40     1.78     0.055       0.89     1.27     0.035       -     1.02     -

#### Notes

• Dimension L3 is for reference only

• Dimension D1 and E1 on type A and B is the same



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### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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